



AI-Enabled Internet of Things for Engineering Applications

Guest Editors:

Prof. Dr. Moongu Jeon

Gwangju Institute of Science and
Technology, Gwangju 61005,
Korea

Dr. Jeonghwan Gwak

Department of Software, Korea
National University of
Transportation, Chungju 27469,
Republic of Korea

Deadline for manuscript
submissions:

closed (20 August 2023)

Message from the Guest Editors

Dear Colleagues,

The synergetic relationship between Artificial Intelligence (AI) and Internet of Things (IoT) enables disruptive innovations in wearables and implantable devices for numerous engineering applications. The three key components of this emerging era of AI and IoT applications are (i) intelligent sensors, information and knowledge, (ii) intelligent systems-of-systems, and (iii) advanced end-to-end analytics. There are several research challenges in implementing AI-enabled IoT systems and applications. From a system and application front, there is a need to design intelligent and scalable data solutions and analytics facilitated by collaborative sensing and collaborative machine learning algorithms. For this reason, this Special Issue aims to solicit submissions of unpublished and original research articles that present in-depth fundamental research contributions from a methodological or theoretical application perspective containing novel algorithms, architectures, techniques, or systems that offer new insights and findings in the field of AI-empowered IoT.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q1 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Contact Us

Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](#)